



Advance Product Change Notification

201506030A

Issue Date: 07-Jul-2015

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QUALITY

Management Summary

Introduction of Dual Source for the CAN transceiver TJA1051 die used in the LPC11C24FBD48/301 and LPC11C22FBD48/301 multi chip modules

Change Category

- | | | | |
|--|---|---|--|
| <input type="checkbox"/> Wafer Fab process | <input type="checkbox"/> Assembly Process | <input type="checkbox"/> Product Marking | <input type="checkbox"/> Design |
| <input type="checkbox"/> Wafer Fab materials | <input type="checkbox"/> Assembly Materials | <input type="checkbox"/> Electrical spec./Test coverage | <input type="checkbox"/> Mechanical Specification |
| <input checked="" type="checkbox"/> Wafer Fab location | <input type="checkbox"/> Assembly Location | <input type="checkbox"/> Test Location | <input type="checkbox"/> Packing/Shipping/Labeling |

LPC11C2x FBD48/301 Dual Source of CAN Transceiver Die

Details of this Planned Change

A dual source has been established and qualified for the TJA1051 and TJA1051 CAN transceiver products in September, 2014. See Final Process Change Notification 201301011F05. This dual source will be extended for use in the LPC11C24FBD48/301 and LPC11C22FBD48/301 multi chip modules. Die from the 2nd location wafer fab SSMC, Singapore, will be used in parallel to the running production in wafer fab ICN8, Nijmegen, the Netherlands. The actual sourcing of the die is at NXP's discretion.

Attached to this PCN is the Self Qualification Plan which describes the testing to be implemented to qualify this change.

Production first shipments 25-Nov-2015 or earlier based on customer acceptance.

Why do we Plan this Change

To provide additional capacity and continuity of supply.

Identification of Affected Products

Product identification does not change

Wafer fab can be traced by manufacturing date code. Parts built with date code 1521 and later may be sourced from either wafer fab.

Product Availability

Sample Information

Samples are available upon request

Production

Planned first shipment 25-Nov-2015

Impact

no impact to the product's functionality anticipated.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Timing and Logistics

The Self Qualification Report will be ready on 12-Aug-2015.

The Final PCN is planned to be issued on: 14-Aug-2015.

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 06-Aug-2015.

Planned Shipment 25-November-2015 or earlier based on customer acceptance.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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Position Senior Quality Engineer
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NXP Quality Management Team.

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